

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**Priority** Application Serial No. .... 09/518,511  
**Priority** Filing Date ..... March 3, 2000  
Inventor ..... Dinesh Chopra  
Assignee ..... Micron Technology, Inc.  
**Priority** Group Art Unit ..... 2825  
**Priority** Examiner ..... L. Malsawma  
Attorney's Docket No. .... MI22-2345  
Title: Conductive Connection Forming Methods, Oxidation Reducing Methods, and  
Integrated Circuits Formed Thereby

**PRELIMINARY AMENDMENT**

To: MS Patent Application  
Commissioner for Patents  
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**Introductory Comments**

The present Response is submitted in the Revised Amendment Format and  
therefore qualifies for waiver of provisions 37 CFR 1.121(a), (b), (c) and (d).

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